T0-220

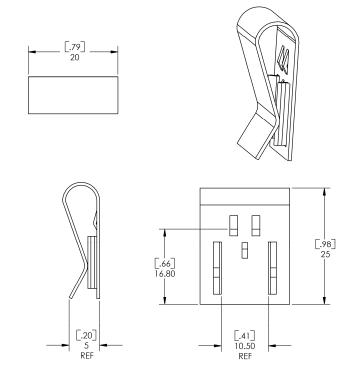
Board Level Heat Sinks



ThermaFlo

P/N: 832202B00000





PRODUCT SPECIFICATIONS

• Devices: TO-220

Size: 20.0 x 5.0 x 25.0 mmMaterial: Aluminum, 0.8 mm thick

Type: Stamped

Finish: Black Anodized

• PCB Mounting: Device Leads

IC Mounting: Integrated Spring

· Package: Bulk

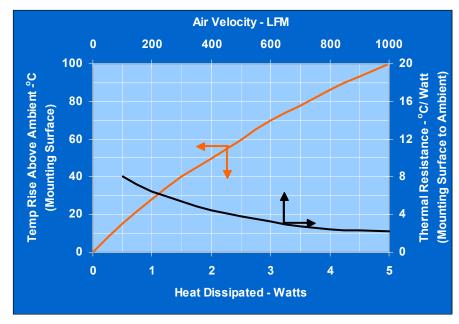
FEATURES & BENEFITS

- · No Hardware Device Attachment
- Constant Spring Force Tension
- Device Alignment Rails
- RoHS Compliant



CUSTOMIZED HEATSINKS

- · Specialized Plating
- Specialized Body Configurations
- · Contact Applications Engineering



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